Title (en)

BATH FOR THE GALVANIC DEPOSITION OF GOLD ALLOYS AND THE USE THEREOF

Title (de)

BAD ZUR GALVANISCHEN ABSCHEIDUNG VON GOLDLEGIERUNGEN SOWIE DESSEN VERWENDUNG

Title (fr)

BAIN ELECTROLYTIQUE POUR DEPOSER DES ALLIAGES EN OR ET SON UTILISATION

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Abstract (en)

[origin: WO02068728A1] The invention relates to a bath for the galvanic deposition of gold and gold alloys, and to the use thereof for producing dental shaped elements, wherein the gold is present in the form of a gold sulfite complex. The inventive bath and the inventive use are characterized in that at least one bismuth compound is present in addition to the optional other metals and conventional additives for gold sulfites of the above-described kind. The bismuth compound is preferably a complex compound, especially one that contains the complexing agents NTA, HEDTA, TEPA, DTPA, EDNTA or EDTA. The invention has several advantages, the most important being that the bismuth can be added to the bath already when it is prepared. The invention provides for a bath that is functional for a long period and that does not necessarily require the addition of other additives before galvanization.

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